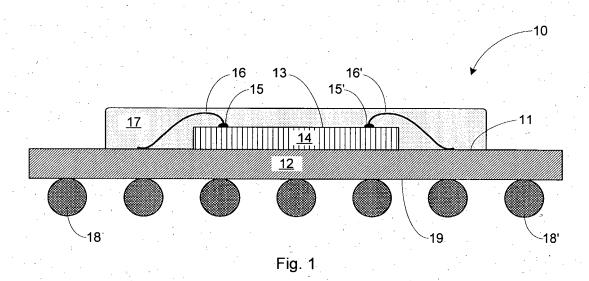
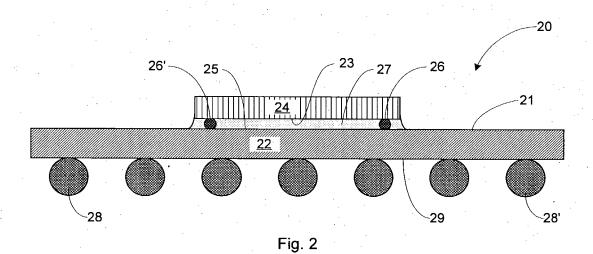
Inventor: Pendse
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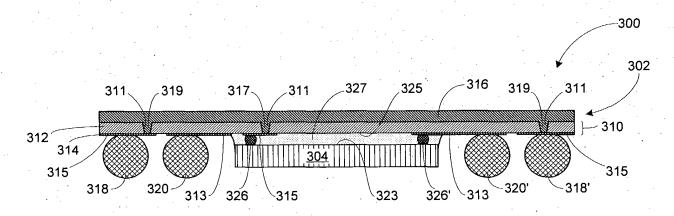


Fig. 3

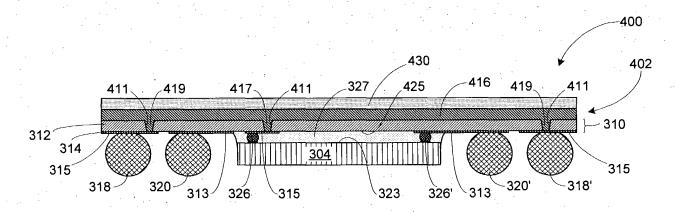


Fig. 4

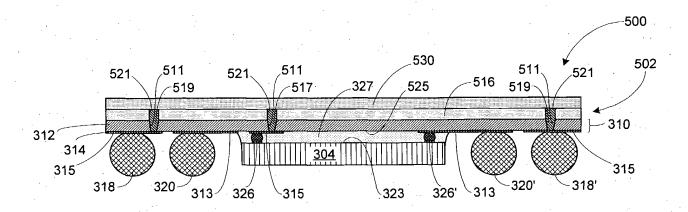


Fig. 5:

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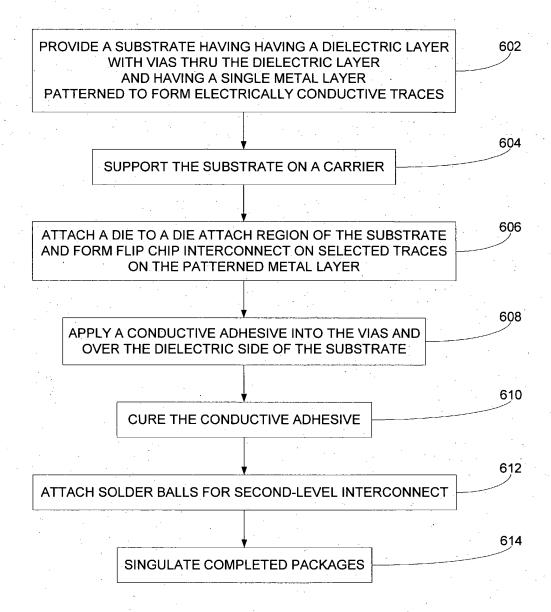


Fig. 6

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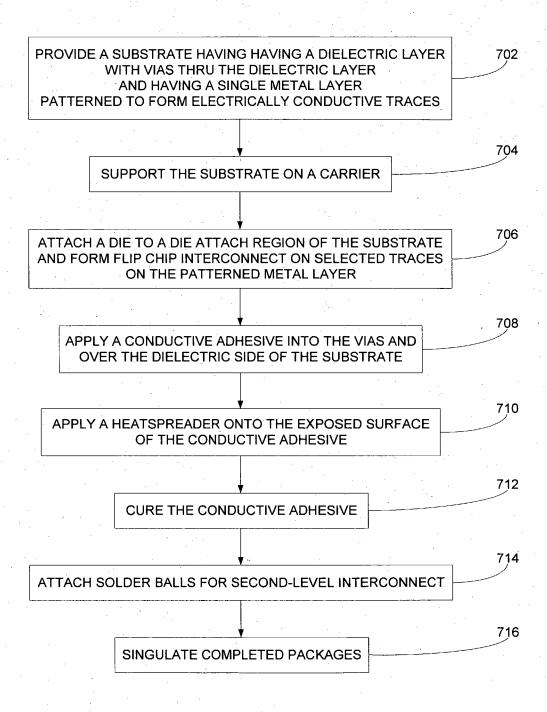


Fig. 7

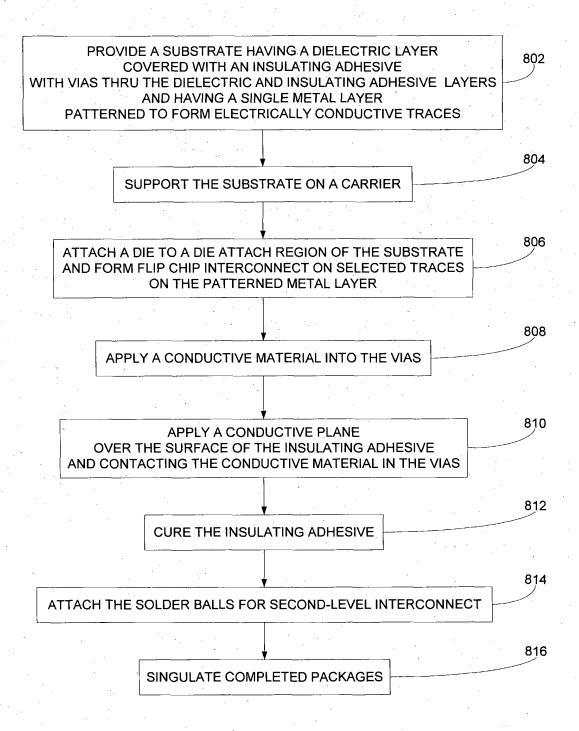


Fig. 8